	REVISIONS		
LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
Α	Add case outline letter "H". Delete outline letter "G". Make change to 1.2.4, 1.3, table I, and figure 1. Make change to table IIC. In accordance with N.O.R. 5962-R008-94.	93-10-19	M. A. FRYE
В	Make change to 1.3, and supply current test as specified under table I. In accordance with N.O.R. 5962-R164-95.	95-06-28	M. A. FRYE
С	Add device types 02 and 03. Make changes to 1.3, table I, figure 1, and table II. Redrawn.	96-10-22	R. MONNIN

THE ORIGINAL FIRST SHEET OF THIS DRAWING HAS BEEN REPLACED.

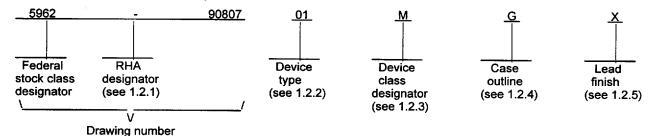
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STANDARD MICROCIRCUIT DRAWING  THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE  AMSC N/A		Т	CHECKED BY RAJESH PITHADIA  APPROVED BY RAYMOND MONNIN																	
		BLE					MICROCIRCUIT, LINEAR, JFET, MICROPOWER, OPERATIONAL AMPLIFIER, MONOLITHIC SILICON													
		- 1	DRA	WING	APPRO		ATE													
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<u>DISTRIBUTION STATEMENT A</u>. Approved for public release; distribution is unlimited.

5962-E011-97

# 1. SCOPE

- 1.1 <u>Scope</u>. This drawing documents two product assurance class levels consisting of high reliability (device classes Q and M) and space application (device class V). A choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels are reflected in the PIN.
  - 1.2 PIN. The PIN is as shown in the following example:



- 1.2.1 <u>RHA designator</u>. Device classes Q and V RHA marked devices meet the MIL-PRF-38535 specified RHA levels and are marked with the appropriate RHA designator. Device class M RHA marked devices meet the MIL-PRF-38535, appendix A specified RHA levels and are marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.
  - 1.2.2 <u>Device type(s)</u>. The device type(s) identify the circuit function as follows:

Device type	Generic number	Circuit function
01	TLE2061M	JFET-input high output drive micropower operational amplifier
02	TLE2061AM	JFET-input high output drive micropower operational amplifier
03	TLE2061BM	JFET-input high output drive micropower operational amplifier

1.2.3 <u>Device class designator</u>. The device class designator is a single letter identifying the product assurance level as follows:

# Device class

# **Device requirements documentation**

М

Vendor self-certification to the requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A

Q or V

Certification and qualification to MIL-PRF-38535

1.2.4 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
G	MACY1-X8	8	Can
Н	GDFP1-F10 or CDFP2-F10	10	Flat pack
P	GDIP1-T8 or CDIP2-T8	8	Dual-in-line
2	CQCC1-N20	20	Square leadless chip carrier

1.2.5 <u>Lead finish</u>. The lead finish is as specified in MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

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			· · · · · · · · · · · · · · · · · · ·
1.3 <u>Abşolute maximum ratings</u> . <u>1</u> / <u>2</u> /			
Supply volatoe (+\/ )	.4034.4		•
Supply volatge (+V <sub>CC</sub> )	+19 V dc		
I Differential input voltage 3/	<b>+38 // 4</b> 2		
Input voltage range (V <sub>I</sub> ) (any input)	+Vaa		
input current (ii) (each input)	±1 mA		
Output current (IO)	±80 mA		
l otal current into +V <sub>CC</sub> terminal	80 mA		
Total current into -V <sub>CC</sub> terminal	80 mA		
Duration of short circuit current at ( or below) +25°C 4/	Unlimited		
Storage temperature range	65°C to +15	0°C	
Case 2	+360°C		
Lead temperature, soldering 6 mm (1/16 inch) from	+200°C		
case for 60 seconds:			
Cases G, H, and P			
Junction temperature	+150°C		
Power dissipation (P <sub>D</sub> )			
Case G <u>5</u> /	650 mW		
Case H <u>5</u> /	675 mW		
Case P <u>5</u> /	1050 mW		
Case 2 <u>5</u> /	1375 mW	1000	
morniar resistance, junction-to-case (OJC)	See MiL-STD	-1835	
1.4 Recommended operating conditions.			
Supply voltage (±V <sub>CC</sub> )	+3.5 V dc min	imum +18 \/ do movimum	
Common-mode input voltage (V <sub>IC</sub> ) (+V <sub>CC</sub> = 5 V)	1.6 V dc min	imum, ±10 v dc maximum	
Common-mode input voltage $(V_{IC})$ (+ $V_{CC}$ = ±15 V)	11 V dc minis	mum 13 V dc mavimum	
Ambient operating free-air temperature (1 <sub>A</sub> )	55°C to +125	5°C	
Source resistance from ground to input terminals (R <sub>S</sub> ) .	50 Ω		
2. APPLICABLE DOCUMENTS			
2.1 Government specification, standards, and handbooks. The part of this drawing to the output and if the said	he following spec	ification, standards, and ha	andbooks form a
part of this drawing to the extent specified herein. Unless other the issue of the Department of Defense Index of Specifications solicitation	Wise specified th	a issues of these decumen	رز ليستميزا سمسمات معمره
solicitation.	and Standards (D	obios) and supplement th	ereto, cited in the
ODEOUEIOATION			
SPECIFICATION			
MILITARY			
MIL-PRF-38535 - Integrated Circuits, Manufacturing, G	onoral Cassificati	<b>6</b>	
mile 7 km 30000 milling aled Circuits, Manufacturing, G	eneral Specification	on tor.	
1/ Stresses above the absolute maximum rating may cause proving the levels may be a series of the se	ermanent damage	to the device. Extended of	peration at the
Illiaxilliulli levels illav dediade benormance and affect reliai	hility		
<ul> <li>All voltage values, except differential voltages, are with responsible.</li> <li>Differential voltages are at the noninverting input with responsible.</li> </ul>	ect to the inverting	input	C.
4/ I he output may be shorted to either supply. Temperature a	and supply voltage	must be limited to ensure	that the maximum
dissipation rating is not exceeded.			
5/ Above T <sub>A</sub> = +25°C derate at a factor of 5.2 mW/°C for case 11 mW/°C for case 2.	G, 5.4 mW/°C fo	r case H, 8.4 mW/°C for ca	ase P and
THE TO LOT COSC 2.			
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# **STANDARDS**

#### **MILITARY**

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

MIL-STD-973 - Configuration Management. MIL-STD-1835 - Microcircuit Case Outlines.

# **HANDBOOKS**

# **MILITARY**

MIL-HDBK-103 - List of Standard Microcircuit Drawings (SMD's).

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Unless otherwise indicated, copies of the specification, standards, and handbooks are available from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

# 3. REQUIREMENTS

- 3.1 <u>Item requirements</u>. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 and as specified herein or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. The individual item requirements for device class M shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes Q and V or MIL-PRF-38535, appendix A and herein for device class M.
  - 3.2.1 <u>Case outline(s)</u>. The case outline(s) shall be in accordance with 1.2.4 herein.
  - 3.2.2 <u>Terminal connections</u>. The terminal connections shall be as specified on figure 1.
  - 3.2.3 <u>Test circuits</u>. The test circuits shall be as specified on figure 2.
- 3.3 <u>Electrical performance characteristics and postirradiation parameter limits</u>. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table IIA. The electrical tests for each subgroup are defined in table I.

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TABLE I. Electrical performance characteristics.

Test	Symbol		Group A	Device	Lir	imits	Unit
		-55°C ≤ T <sub>A</sub> ≤+125°C unless otherwise specified	subgroups	type	Min	Max	1
Input offset voltage	Vio	$V_{CC} = \pm 5 \text{ V}, V_{IC} = 0 \text{ V},$ $R_S = 50 \Omega$	1	01		3.1	m∨
			2,3	] '		6	1
		$V_{CC} = \pm 15 \text{ V}, V_{IC} = 0 \text{ V},$ R <sub>S</sub> = 50 \(\Omega\)	1	] '		3	1
			2,3			6	
		$V_{CC} = \pm 5 \text{ V}, V_{IC} = 0 \text{ V},$ R <sub>S</sub> = 50 \(\Omega\)	1	02		2.6	m∨
			2,3	] '		4.6	]
		$V_{CC} = \pm 15 \text{ V}, V_{IC} = 0 \text{ V},$ R <sub>S</sub> = 50 \(\Omega\)	1	] !		1.5	
	İ		2,3			3.6	
		$V_{CC} = \pm 5 \text{ V}, V_{IC} = 0 \text{ V},$ $R_S = 50 \Omega$	1	03		1.9	mV
			2,3			3.1	
		$V_{CC} = \pm 15 \text{ V, } V_{IC} = 0 \text{ V,}$ R <sub>S</sub> = 50 \(\Omega\)	1			0.5	İ
	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	2,3			1.7		
Input offset current	lio	$V_{CC} = \pm 5 \text{ V}, V_{IC} = 0 \text{ V}, R_S = 50 \Omega$	2,3	All		15	nA
		$V_{CC} = \pm 15 \text{ V}, V_{IC} = 0 \text{ V}, R_S = 50 \Omega$	2,3			20	
Input bias current	<sup>I</sup> IB	$V_{CC} = \pm 5 \text{ V}, V_{IC} = 0 \text{ V},$ R <sub>S</sub> = 50 $\Omega$	2,3	All		30	nA
		$V_{CC} = \pm 15 \text{ V, V}_{IC} = 0 \text{ V,}$ R <sub>S</sub> = 50 $\Omega$	2,3			40	
Common-mode input voltage range	V <sub>ICR</sub>	V <sub>CC</sub> = ±5 V	1,2,3	All	-1.6 to 4		V
		V <sub>CC</sub> = ±15 V	1,2,3		-11 to 13		
Maximum positive peak output voltage swing	<sup>+V</sup> OM	$V_{CC}$ = ±5 V, $R_L$ = 10 k $\Omega$	1	All		3.5	V
output voitage swing			2,3			3	ĺ
		$V_{CC} = \pm 5 \text{ V}, R_{L} = 600 \Omega$	1			2.5	1
		1	2,3	<i>i</i> [		2	1

See footnotes at end of table.

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TABLE I. Electrical performance characteristics - Continued. Group A Device Limits Unit Test Symbol Conditions -55°C ≤ T<sub>A</sub> ≤+125°C unless otherwise specified subgroups type Min Max  $V_{CC} = \pm 15 \text{ V, R}_{L} = 10 \text{ k}\Omega$ ΑII ٧ 13 Maximum positive peak +V<sub>ОМ</sub> 1 output voltage swing 2,3 12.5  $V_{CC} = \pm 15 \text{ V, R}_1 = 600 \Omega$ 1 12.5 2.3 12 -V<sub>OM</sub> ٧  $V_{CC}$  = ±5 V,  $R_L$  = 10 k $\Omega$ All -3.5Maximum negative peak 1 output voltage swing 2,3 -3  $V_{CC}$  = ±5 V,  $R_L$  = 600  $\Omega$ 1 -2.5 2,3 -2  $V_{CC}$  = ±15 V,  $R_L$  = 10 k $\Omega$ 1 -13 -12.52,3  $V_{CC}$  = ±15 V,  $R_L$  = 600  $\Omega$ -12.5 1 -12 2,3  $V_{CC} = \pm 5 \text{ V}, V_{O} = \pm 2.8 \text{ V},$   $R_{L} = 10 \text{ k}\Omega$  $A_{VD}$ 1 Αll 15 V/mV Large signal differential voltage amplification 2.3 2  $V_{CC} = \pm 5 \text{ V}, R_{L} = 600 \Omega, V_{O} = 0 \text{ V to } 2.5 \text{ V}$ 1 1 2,3 0.5  $V_{CC}$  = ±5 V, R<sub>L</sub> = 600  $\Omega$ , V = 0 V to -2.5 V 1 2,3 0.5  $V_{CC} = \pm 15 \text{ V}, V_{O} = \pm 10 \text{ V},$   $R_{L} = 10 \text{ k}\Omega$ 1 30 2,3 20  $V_{CC}$  = ±15 V,  $R_L$  = 600  $\Omega$ ,  $V_O$  = 0 V to 8 V 1 25 2,3 7  $V_{CC} = \pm 15 \text{ V}, R_L = 600 \Omega, V_O = 0 \text{ V to -8 V}$ 3 1 2.3  $\begin{array}{l} V_{CC} = \pm 5 \text{ V, R}_{L} = 50 \text{ }\Omega, \\ V_{IC} = V_{ICR} \text{ minimum} \end{array}$ **CMRR** 1 All 65 dΒ Common-mode rejection ratio 2,3 60  $\begin{array}{l} V_{CC} = \pm 15 \text{ V, R}_{L} = 50 \text{ }\Omega, \\ V_{IC} = V_{ICR} \text{ minimum} \end{array}$ 72 1 2,3 65 See footnotes at end of table. SIZE STANDARD 5962-90807 Α **MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS** 

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TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions	Group A	Device	Limits		Unit
		-55°C ≤ T <sub>A</sub> ≤+125°C unless otherwise specified	subgroups	type	Min	Max	1
Supply-voltage rejection ratio (Δ±V <sub>CC</sub> / ΔV <sub>IO</sub> )	k <sub>SVR</sub>	$V_{CC} = \pm 5 \text{ V or } \pm 15 \text{ V},$ $R_S = 50 \Omega$	1	All		75	dB
		KS = 50 17	2,3	]		65	1
Supply current	<sup>1</sup> cc	$V_{CC} = \pm 5 \text{ V}, V_{O} = 0 \text{ V},$ no load	1	All		325	μА
			2,3			350	1
		$V_{CC} = \pm 15 \text{ V}, V_{O} = 0 \text{ V},$ no load	1			350	1
	<u> </u>		2,3			375	
Slew rate at unity gain 1/	SR	$V_{CC} = \pm 15 \text{ V}, R_L = 10 \text{ k}\Omega,$ $C_L = 100 \text{ pF}$	4	All	2		V/µs
	1 1	C <sub>L</sub> = 100 pr	5,6		1.8		1

1/ See figure 2.

- 3.5 <u>Marking</u>. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-HDBK-103. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes Q and V shall be in accordance with MIL-PRF-38535. Marking for device class M shall be in accordance with MIL-PRF-38535, appendix A.
- 3.5.1 <u>Certification/compliance mark</u>. The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-PRF-38535. The compliance mark for device class M shall be a "C" as required in MIL-PRF-38535, appendix A.
- 3.6 <u>Certificate of compliance</u>. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein). For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6.2 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and herein or for device class M, the requirements of MIL-PRF-38535, appendix A and herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 or for device class M in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 <u>Notification of change for device class M</u>. For device class M, notification to DSCC-VA of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change as defined in MIL-STD-973.
- 3.9 <u>Verification and review for device class M.</u> For device class M, DSCC, DSCC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
- 3.10 <u>Microcircuit group assignment for device class M</u>. Device class M devices covered by this drawing shall be in microcircuit group number 61 (see MIL-PRF-38535, appendix A).

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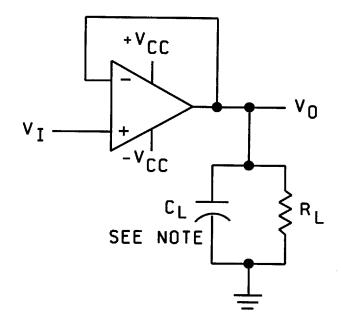
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Device types		All	
Case outlines	G and P	Н	2
Terminal number		Terminal symbol	
1	OFFSET N1	NC	NC
2	-INPUT 1	OFFSET N1	OFFSET N1
3	+INPUT 1	-INPUT	NC
4	-v <sub>cc</sub>	+INPUT	NC
5	OFFSET N2	-V <sub>CC</sub>	-INPUT
6	OUTPUT	OFFSET N2	NC
7	+V <sub>CC</sub>	OUTPUT	+INPUT
8	NC	+V <sub>CC</sub>	NC
9		NC	NC
10		NC	-v <sub>cc</sub>
11			NC
12			OFFSET N2
13			NC
14			NC
15			OUTPUT
16			NC
17			+V <sub>CC</sub>
18			NC
19			NC
20			NC

NC = No connection

FIGURE 1. <u>Terminal connections</u>.

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NOTE:  $C_L$  includes fixture capacitance.

FIGURE 2. Test circuits.

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#### 4. QUALITY ASSURANCE PROVISIONS

- 4.1 <u>Sampling and inspection</u>. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. For device class M, sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.
- 4.2 <u>Screening</u>. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection.

# 4.2.1 Additional criteria for device class M.

- a. Burn-in test, method 1015 of MIL-STD-883.
  - (1) Test condition B or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015.
  - (2)  $T_{\Delta} = +125^{\circ} \text{C}$ , minimum.
- b. Interim and final electrical test parameters shall be as specified in table IIA herein.

# 4.2.2 Additional criteria for device classes Q and V.

- a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
- b. Interim and final electrical test parameters shall be as specified in table IIA herein.
- Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.
- 4.3 Qualification inspection for device classes Q and V. Qualification inspection for device classes Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).
- 4.4 <u>Conformance inspection</u>. Technology conformance inspection for classes Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections and as specified herein except where option 2 of MIL-PRF-38535 permits alternate in-line control testing. Quality conformance inspection for device class M shall be in accordance with MIL-PRF-38535, appendix A and as specified herein. Inspections to be performed for device class M shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

#### 4.4.1 Group A inspection.

- a. Tests shall be as specified in table IIA herein.
- b. Subgroups 7, 8, 9, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.

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# TABLE IIA. Electrical test requirements.

Test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)	Subgroups (in accordance with MIL-PRF-38535, table III)	
	Device class M	Device class Q	Device class V
Interim electrical parameters (see 4.2)			1
Final electrical parameters (see 4.2)	1,2,3,4 <u>1</u> /	1,2,3,4 <u>1</u> /	1,2,3,4 <u>1</u> /
Group A test requirements (see 4.4)	1,2,3,4,5,6	1,2,3,4,5,6	1,2,3,4,5,6
Group C end-point electrical parameters (see 4.4)	1	1	1 <u>2</u> /
Group D end-point electrical parameters (see 4.4)	1	1	1
Group E end-point electrical parameters (see 4.4)	1,4	1,4	1,4

 1/ PDA applies to subgroup 1 with exception of V<sub>IO</sub>.
 2/ Delta limits in accordance with table IIB shall be computed with reference to the previous interim electrical parameters.

TABLE IIB. Delta limits at +25°C.

Parameter <u>1</u> /	Device types All		
V <sub>IO</sub>	v <sub>cc</sub>	Limit	Delta
	±5 ∨	±5 mV	±1 mV
	±15 V	±4 mV	±1 mV

1/ The above parameter shall be recorded before and after the required life tests to determine the delta.

4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table IIA herein.

4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:

- Test condition B or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
- b.  $T_A = +125^{\circ}C$ , minimum.
- c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

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- 4.4.2.2 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
  - 4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table IIA herein.
- 4.4.4 <u>Group E inspection</u>. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein).
  - a. End-point electrical parameters shall be as specified in table IIA herein.
  - b. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535 for the RHA level being tested. For device class M, the devices shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535, appendix A for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at T<sub>A</sub> = +25°C ±5°C, after exposure, to the subgroups specified in table IIA herein.
  - c. When specified in the purchase order or contract, a copy of the RHA delta limits shall be supplied.
  - 5. PACKAGING
- 5.1 <u>Packaging requirements</u>. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.
  - 6. NOTES
- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.1.1 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
  - 6.1.2 Substitutability. Device class Q devices will replace device class M devices.
- 6.2 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.
- 6.3 <u>Record of users</u>. Military and industrial users should inform Defense Supply Center Columbus when a system application requires configuration control and which SMD's are applicable to that system. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0525.
- 6.4 <u>Comments</u>. Comments on this drawing should be directed to DSCC-VA , Columbus, Ohio 43216-5000, or telephone (614) 692-0674.
- 6.5 <u>Abbreviations, symbols, and definitions</u>. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.
  - 6.6 Sources of supply.
- 6.6.1 <u>Sources of supply for device classes Q and V</u>. Sources of supply for device classes Q and V are listed in QML-38535. The vendors listed in QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DSCC-VA and have agreed to this drawing.
- 6.6.2 <u>Approved sources of supply for device class M</u>. Approved sources of supply for class M are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DSCC-VA.

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#### STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 96-10-22

Approved sources of supply for SMD 5962-90807 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535.

Standard microcircuit drawing PIN <u>1</u> /	Vendor CAGE number	Vendor similar PIN <u>2</u> /
5962-9080701MGA	<u>3</u> /	TLE2061MLB
5962-9080701MHA	01295	TLE2061MUB
5962-9080701MPA	01295	TLE2061MJGB
5962-9080701M2A	01295	TLE2061MFKB
5962-9080702QHA	01295	TLE2061AMUB
5962-9080702QPA	01295	TLE2061AMJGB
5962-9080702Q2A	01295	TLE2061AMFKB
5962-9080703QPA	01295	TLE2061BMJGB

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. The device manufacturers listed herein are authorized to supply alternate lead finishes "A", "B", or "C" at their discretion. Contact the listed approved source of supply for further information.
- 2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- 3/ Not available from an approved source of supply.

Vendor CAGE <u>number</u>

Vendor name and address

01295

Texas Instruments, Incorporation 13500 N. Central Expressway P.O. Box 655303 Dallas, TX 75265

Point of contact: I-20 at FM 1788

Midland, TX 79711-0448

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.